256k SRAM (32-kword  $\times$  8-bit)

# HITACHI

ADE-203-135F (Z) Rev. 6.0 Nov. 13, 1997

#### Description

The Hitachi HM62256B Series is a CMOS static RAM organized 32,768-word  $\times$  8-bit. It realizes higher performance and low power consumption by employing 0.8 µm Hi-CMOS process technology. The device, packaged in 8  $\times$  14 mm TSOP, 8  $\times$  13.4 mm TSOP with thickness of 1.2 mm, 450 mil SOP (foot print pitch width), 600 mil plastic DIP, or 300 mil plastic DIP, is available for high density mounting. It offers low power standby power dissipation; therefore, it is suitable for battery backup systems.

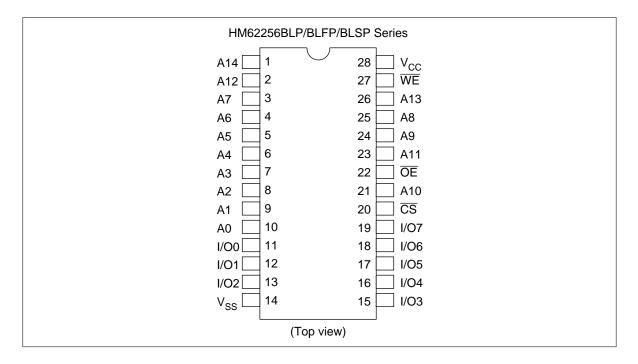
#### Features

- Single 5.0 V supply:  $5.0 \text{ V} \pm 10\%$
- Access time: 55 ns/70 ns/85 ns (max)
- Power dissipation:
  - Active: 25 mW (typ) (f = 1 MHz)
  - Standby:  $1.0 \mu W (typ)$
- Completely static memory
  - No clock or timing strobe required
- Equal access and cycle times
- Common data input and output
  - Three state output
- Directly TTL compatible all inputs and outputs
- Battery backup operation

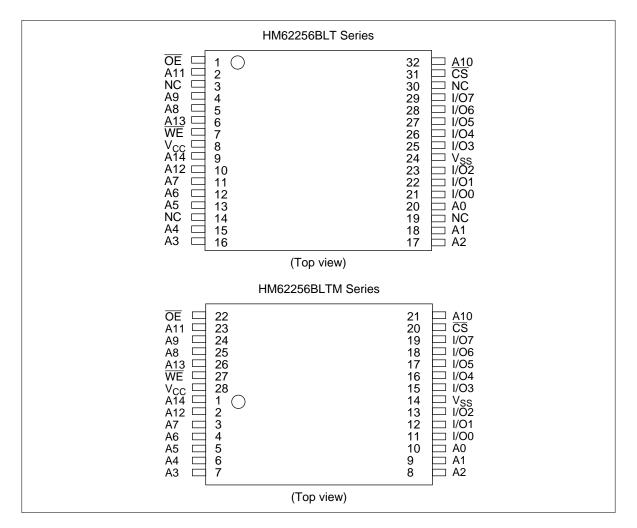
## **Ordering Information**

Туре No.	Access time	Package
HM62256BLP-7	70 ns	600-mil 28-pin plastic DIP (DP-28)
HM62256BLP-7SL	70 ns	
HM62256BLSP-7	70 ns	300-mil 28-pin plastic DIP (DP-28NA)
HM62256BLSP-7SL	70 ns	
HM62256BLFP-7T	70 ns	450-mil 28-pin plastic SOP (FP-28DA)
HM62256BLFP-5SLT	55 ns	
HM62256BLFP-7SLT	70 ns	
HM62256BLFP-7ULT	70 ns	
HM62256BLT-8	85 ns	8 mm $\times$ 14 mm 32-pin TSOP (TFP-32DA)
HM62256BLT-7SL	70 ns	
HM62256BLTM-8	85 ns	8 mm $ imes$ 13.4 mm 28-pin TSOP (TFP-28DA)
HM62256BLTM-5SL	55 ns	
HM62256BLTM-7SL	70 ns	
HM62256BLTM-7UL	70 ns	

#### **Pin Arrangement**



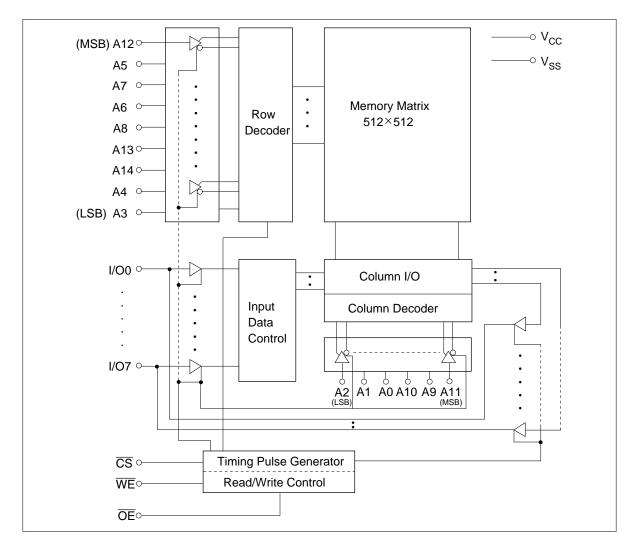
#### Pin Arrangement (cont.)



#### **Pin Description**

Pin Name	Function
A0 to A14	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
WE	Write enable
ŌĒ	Output enable
V <sub>cc</sub>	Power supply
V <sub>ss</sub>	Ground
NC	No connection

## **Block Diagram**



### **Operation Table**

WE	CS	OE	Mode	V <sub>cc</sub> current	I/O pin	Ref. cycle
×	Н	×	Standby	$I_{SB},I_{SB1}$	High-Z	—
Н	L	Н	Output disable	I <sub>cc</sub>	High-Z	_
Н	L	L	Read	I <sub>cc</sub>	Dout	Read cycle (1)to (3)
L	L	Н	Write	I <sub>cc</sub>	Din	Write cycle (1)
L	L	L	Write	I <sub>cc</sub>	Din	Write cycle (2)

Note:  $\times$ : H or L

#### **Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Power supply voltage relative to $\rm V_{ss}$	V <sub>cc</sub>	-0.5 to +7.0	V
Terminal voltage on any pin relative to $V_{\mbox{\scriptsize ss}}$	V <sub>T</sub>	$-0.5^{*1}$ to V <sub>cc</sub> +0.3 <sup>*2</sup>	V
Power dissipation	Ρ <sub>τ</sub>	1.0	W
Operating temperature range	Topr	0 to +70	°C
Storage temperature range	Tstg	-55 to +125	°C
Storage temperature range under bias	Tbias	-10 to +85	°C

Notes: 1.  $V_{T}$  min: -3.0 V for pulse half-width  $\leq$  50 ns

2. Maximum voltage is 7.0 V

### **DC Operating Conditions** (Ta = 0 to $+70^{\circ}$ C)

Parameter	Symbol	Min	Тур	Max	Unit	Notes
Supply voltage	V <sub>cc</sub>	4.5	5.0	5.5	V	
	V <sub>ss</sub>	0	0	0	V	
Input high voltage	V <sub>IH</sub>	2.2	_	V <sub>cc</sub> + 0.3	V	
Input low voltage	V <sub>IL</sub>	-0.5*1	_	0.8	V	

Note: 1.  $V_{IL}$  min: -3.0 V for pulse half-width  $\leq$  50 ns

Paramete	r	Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leaka	age current	I <sub>LI</sub>	_	_	1	μA	Vin = $V_{ss}$ to $V_{cc}$
Output lea	kage current	I <sub>LO</sub>		—	1	μA	$\overline{\overline{CS}} = V_{IH} \text{ or } \overline{\overline{OE}} = V_{IH} \text{ or } \overline{\overline{WE}} = V_{IL},$ $V_{IO} = V_{SS} \text{ to } V_{CC}$
Operating	current	I <sub>cc</sub>		6	15	mA	$\overline{CS} = V_{IL}, \text{ Others} = V_{IH}/V_{IL},$ $I_{I/O} = 0 \text{ mA}$
Average operating current	HM62256B-5	I <sub>CC1</sub>	—	_	60	mA	$\frac{\text{Min cycle, duty} = 100\%, I_{I/O} = 0 \text{ mA,}}{\overline{\text{CS}} = V_{IL}, \text{ Others} = V_{IH}/V_{IL}}$
	HM62256B-7	I <sub>CC1</sub>	_	33	60	mA	_
	HM62256B-8	I <sub>CC1</sub>	_	29	50	mA	_
		I <sub>CC2</sub>		5	15	mA	$\label{eq:cycle time = 1 } \frac{\text{Cycle time = 1 } \mu \text{s}, \ I_{\text{I/O}} = 0 \ \text{mA}, \\ \overline{\text{CS}} = \text{V}_{\text{IL}}, \ \text{V}_{\text{IH}} = \text{V}_{\text{CC}}, \ \text{V}_{\text{IL}} = 0 }$
Standby c	urrent	I <sub>SB</sub>	_	0.3	2	mA	$\overline{\text{CS}} = \text{V}_{\text{IH}}$
		I <sub>SB1</sub>	_	0.2	100	μA	$Vin \ge 0 \text{ V},  \overline{CS} \ge V_{\text{CC}} - 0.2 \text{ V}$
		I <sub>SB1</sub>		0.2*2	50* <sup>2</sup>	μA	_
		I <sub>SB1</sub>		0.2*3	10* <sup>3</sup>	μA	_
Output low	v voltage	V <sub>OL</sub>	_		0.4	V	I <sub>OL</sub> = 2.1 mA
Output hig	h voltage	V <sub>OH</sub>	2.4	_	_	V	I <sub>он</sub> = –1.0 mA

**DC Characteristics** (Ta = 0 to +70°C,  $V_{CC} = 5 V \pm 10\%$ ,  $V_{SS} = 0 V$ )

Notes: 1. Typical values are at  $V_{cc}$  = 5.0 V, Ta = +25°C and not guaranteed.

2. This characteristic is guaranteed only for L-SL version.

3. This characteristic is guaranteed only for L-UL version.

#### **Capacitance** (Ta = $25^{\circ}$ C, f = 1.0 MHz)

Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Input capacitance*1	Cin		_	8	pF	Vin = 0 V
Input/output capacitance*1	CI/O	_	_	10	pF	$V_{I/O} = 0 V$

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C,  $V_{\rm CC}$  = 5.0 V ± 10%)

#### **Test Conditions**

- Input pulse levels: 0.8 V to 2.4 V
- Input rise and fall time: 5 ns
- Input and output timing reference levels: 1.5 V
- Output load: 1 TTL Gate +  $C_L$  (50 pF) (HM62256B-5) 1 TTL Gate +  $C_L$  (100 pF) (HM62256B-7/8) (Including scope & jig)

#### **Read Cycle**

		HM62256B							
		-5		-7		-8		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	55		70	_	85		ns	
Address access time	t <sub>AA</sub>	—	55		70	_	85	ns	
Chip select to access time	t <sub>ACS</sub>	_	55	_	70	—	85	ns	
Output enable to output valid	t <sub>oe</sub>		35		40		45	ns	
Chip select to output in low-Z	t <sub>cLZ</sub>	5	_	10		10		ns	2
Output enable to output in low-Z	t <sub>oLZ</sub>	5		5		5		ns	2
Chip deselect to output in high-Z	t <sub>CHZ</sub>	0	20	0	25	0	30	ns	1, 2
Output disable to output in high-Z	t <sub>oHZ</sub>	0	20	0	25	0	30	ns	1, 2
Output hold from address change	t <sub>oH</sub>	5		5		5		ns	

#### Write Cycle

		HM6	2256B						
		-5		-7		-8		-	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write cycle time	t <sub>wc</sub>	55		70	_	85		ns	
Chip selection to end of write	t <sub>cw</sub>	40		60		75	_	ns	5
Address setup time	t <sub>AS</sub>	0		0		0	_	ns	6
Address valid to end of write	t <sub>AW</sub>	40		60		75		ns	
Write pulse width	t <sub>wP</sub>	35		50		55	_	ns	4, 13
Write recovery time	t <sub>wR</sub>	0		0	_	0	_	ns	7
Write to output in high-Z	t <sub>wHZ</sub>	0	20	0	25	0	30	ns	1, 2, 8
Data to write time overlap	t <sub>DW</sub>	25		30		35		ns	
Data hold from write time	t <sub>DH</sub>	0		0	_	0	_	ns	
Output active from end of write	t <sub>ow</sub>	5		5		5		ns	2
Output disable to output in High-Z	t <sub>oHz</sub>	0	20	0	25	0	30	ns	1, 2, 8

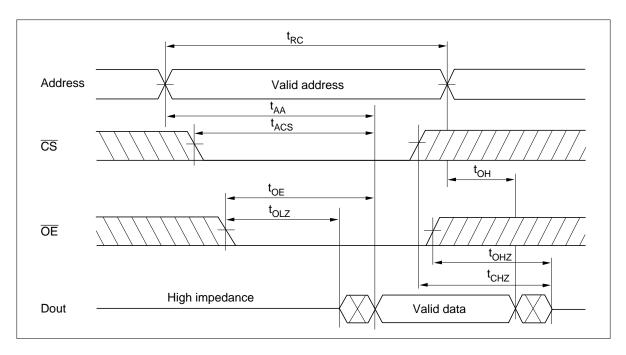
Notes: 1.  $t_{CHZ}$ ,  $t_{OHZ}$  and  $t_{WHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

2. This parameter is sampled and not 100% tested.

- 3. Address must be valid prior to or simultaneously with  $\overline{CS}$  going low.
- 4. A write occurs during the overlap of a low CS and a low WE. A write begins at the latest transition of CS going low or WE going low. A write ends at the earliest transition of CS going high or WE going high. t<sub>wP</sub> is measured from the beginning of write to the end of write.
- 5.  $t_{cw}$  is measured from  $\overline{CS}$  going low to the end of write.
- 6.  $t_{AS}$  is measured from the address valid to the beginning of write.
- 7.  $t_{wR}$  is measured from the earliest of  $\overline{CS}$  or  $\overline{WE}$  going high to the end of write cycle.
- 8. During this period, I/O pins are in the output state; therefore, the input signals of the opposite phase to the outputs must not be applied.
- 9. If CS goes low simultaneously with WE going low or after WE going low, the outputs remain in the high impedance state.
- 10. Dout is the same phase of the latest written data in this write cycle.
- 11. Dout is the read data of next address.
- 12. If CS is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 13. In the write cycle with  $\overline{OE}$  low fixed, t<sub>wP</sub> must satisfy the following equation to avoid a problem of data bus contention.

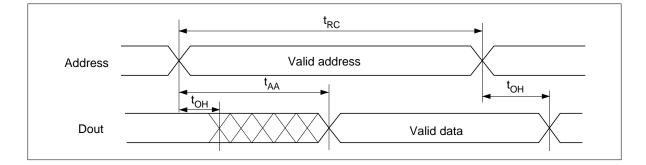
 $t_{_{WP}} \ge t_{_{DW}} \min + t_{_{WHZ}} \max$ 

# **Timing Waveform**

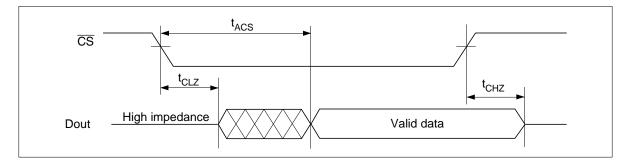


Read Timing Waveform (1)  $(\overline{WE} = V_{IH})$ 

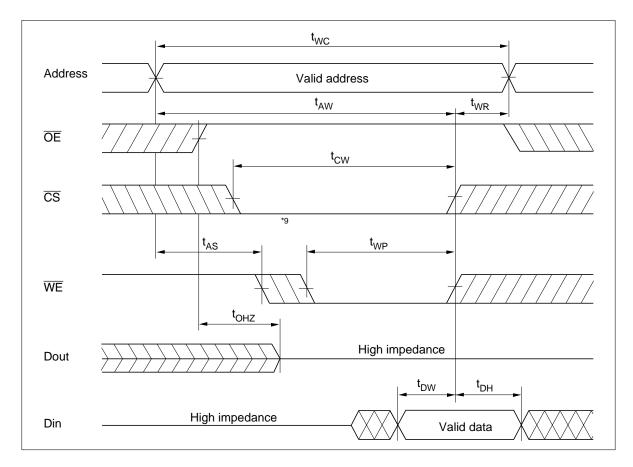
Read Timing Waveform (2) ( $\overline{WE} = V_{II}, \overline{CS} = V_{IL}, \overline{OE} = V_{IL}$ )

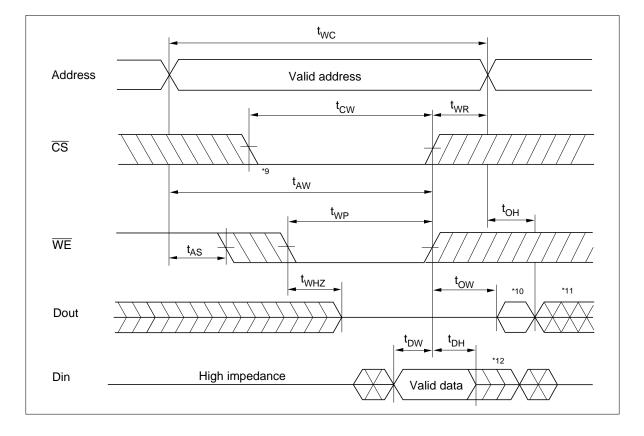


Read Timing Waveform (3)  $(\overline{WE} = V_{IH}, \overline{OE} = V_{IL})^{*3}$ 



Write Timing Waveform (1)  $(\overline{OE} \operatorname{Clock})$ 





#### Write Timing Waveform (2) (OE Low Fixed)

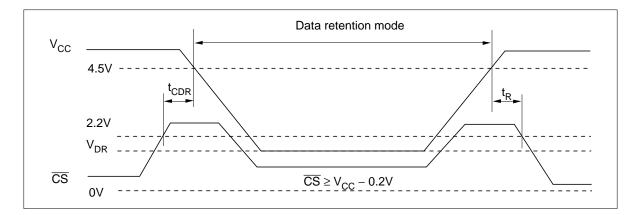
Parameter	Symbol	Min	Typ* <sup>1</sup>	Мах	Unit	Test conditions*6
$V_{cc}$ for data retention	$V_{\text{DR}}$	2.0	—	5.5	V	$\label{eq:cs_cc} \overline{\text{CS}} \geq \text{V}_{\text{cc}} - 0.2 \text{ V}, \\ \text{Vin} \geq 0 \text{V}$
Data retention current	I <sub>CCDR</sub>	_	0.05	<b>30</b> * <sup>2</sup>	μA	$\frac{V_{cc}}{CS} = 3.0 \text{ V}, \text{ Vin} \ge 0\text{V}$ $\overline{CS} \ge V_{cc} - 0.2 \text{ V}$
		_	0.05	10* <sup>3</sup>	μA	
	I	_	0.05	3*4	μA	
Chip deselect to data retention time	t <sub>CDR</sub>	0			ns	See retention Waveform
Operation recovery time	t <sub>R</sub>	t <sub>RC</sub> *5	_		ms	

## Low $V_{cc}$ Data Retention Characteristics (Ta = 0 to 70°C)

Notes: 1. Typical values are at  $V_{cc}$  = 3.0 V, Ta = +25°C and not guaranteed.

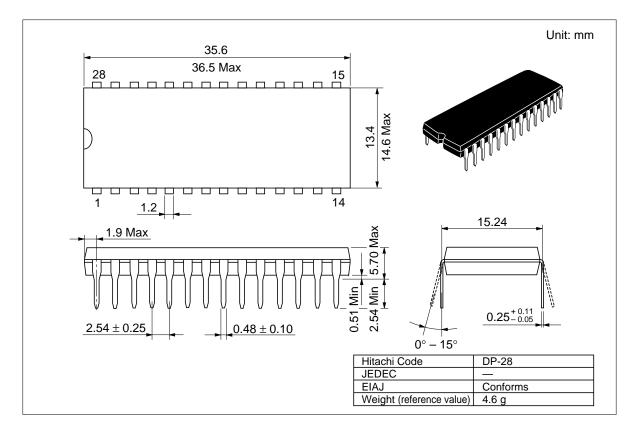
- 2. 10  $\mu$ A max. at Ta = 0 to +40°C.
- 3. This characteristic is guaranteed only for L-SL version, 3  $\mu$ A max. at Ta = 0 to +40°C.
- 4. This characteristic is guaranteed only for L-UL version, 0.6  $\mu$ A max. at Ta = 0 to +40°C.
- 5.  $t_{RC}$  = Read cycle time.
- 6. CS controls address buffer, WE buffer, OE buffer, and Din buffer. If CS controls data retention mode, Vin levels (address, WE, OE, I/O) can be in the high impedance state.

#### Low $\mathbf{V}_{\mathbf{C}\mathbf{C}}$ Data Retention Timing Waveform



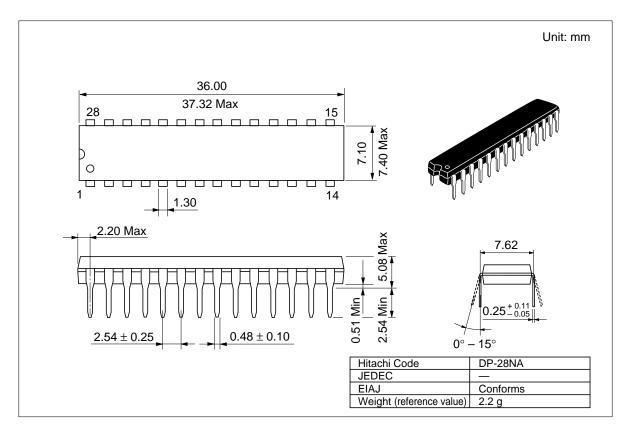
## **Package Dimensions**

#### HM62256BLP Series (DP-28)



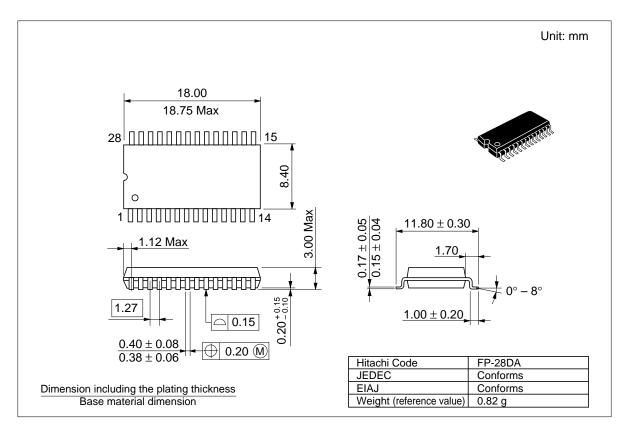
# Package Dimensions (cont.)

#### HM62256BLSP Series (DP-28NA)



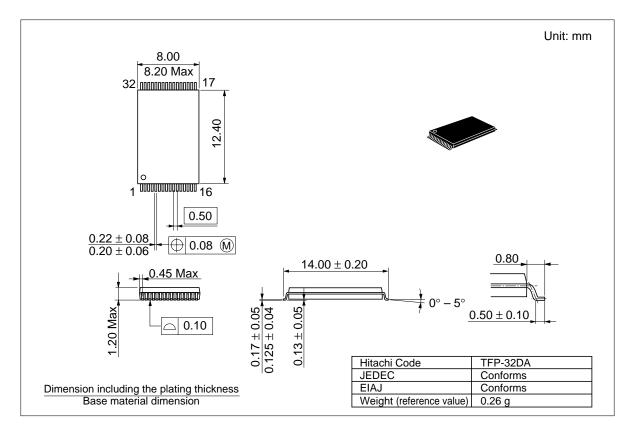
#### Package Dimensions (cont.)

#### HM62256BLFP Series (FP-28DA)



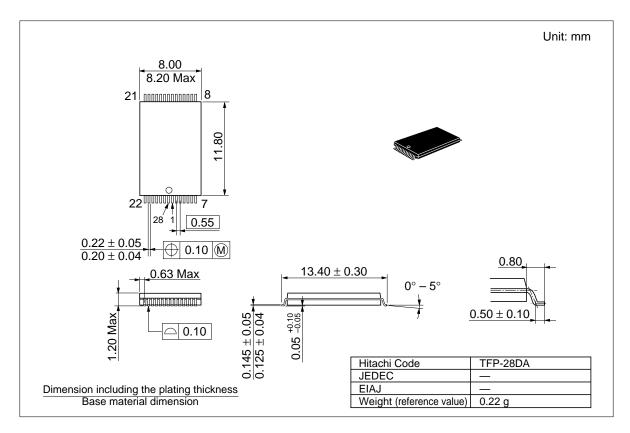
#### Package Dimensions (cont.)

#### HM62256BLT Series (TFP-32DA)



#### Package Dimensions (cont.)

#### HM62256BLTM Series (TFP-28DA)



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## **Revision Record**

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Sep. 10, 1993	Initial Issue	Y. Saito	K. Yoshizaki
1.0	Mar. 23, 1994	DC Characteristics I <sub>cc1</sub> Typ: —/—/— mA to 33/29/26/24 mA	Y. Saito	K. Yoshizaki
2.0	Oct. 31, 1994	Deletion of HM62256BLT-7/10SL/12SL Addition of HM62256BLTM-8/7SL/8SL(TFP-28DA) AC Characteristics Addition of note 12 Low $V_{cc}$ data retention characteristics $V_{DR}$ max: — to 5.5 V Note 2: 20 $\mu$ A max at Ta = 0 to +40°C to 10 $\mu$ A max at Ta = 0 to +40°C Deletion of description; (only for L-version)	Y. Saito	K. Yoshizaki
3.0	Jun. 19, 1995	Change of format Deletion of HM62256BLP-8/10/12/8SL/10SL/12SL Deletion of HM62256BLSP-8/10/12/8SL/10SL/12SL Deletion of HM62256BLFP-8SLT/10SLT/12SLT Deletion of HM62256BLFP-8SLT/10SLT/12SLT Deletion of HM62256BLTM-8SL Addition of HM62256BLTM-8SL Addition of HM62256BLTM-4SLT/5SLT/7ULT Addition of HM62256BLTM-4SLT/5SLT/7ULT Features Fast access time: 70/85/100/120 ns to 45/55/70/85 ns DC Characteristics $I_{CC1}$ typ: 33/29/26/24 mA to//33/29 mA max: 60/50/50/45 mA to 70/60/60/50 mA $I_{SB1}$ typ: 0.3/0.3 $\mu$ A to 0.2/0.2/0.2 $\mu$ A max: 100/50 $\mu$ A to 100/50/10 $\mu$ A Addition of note 3 AC Characteristics Change order of notes. Test Condition Addition of HM62256B-4: 1TTL Gate + C <sub>L</sub> (100pF) (Including scope & jig) $t_{RC}$ min: 70/85/100/120 ns to 45/55/70/85 ns $t_{ACS}$ max: 70/85/100/120 ns to 45/55/70/85 ns $t_{CLZ}$ min: 10/10/10/10 ns to 5/5/10/10 ns $t_{OHZ}$ max: 25/30/35/40 ns to 20/20/25/30 ns $t_{OH}$ min: 5/5/10/10 ns 5/5/55 ns $t_{WC}$ min: 70/85/100/120 ns to 45/55/70/85 ns $t_{CW}$ min: 60/75/80/85 ns to 35/40/60/75 ns $t_{AW}$ min: 60/75/80/85 ns to 35/40/60/75 ns	M. Higuchi	K. Yoshizaki

# Revision Record (cont.)

Rev.	Date	Contents of Modification	Drawn by	Approved by
3.0	Jun. 19, 1995	AC Characteristics $t_{PW}$ min: 30/35/40/50 ns to 20/25/30/35 ns $t_{OHZ}$ max: 25/30/35/40 ns to 20/20/25/30 ns Low V <sub>CC</sub> Data Retention Characteristics Addition of note 4. $t_{CCDR}$ typ: 0.2/0.2 $\mu$ A to 0.05/0.05/0.05 $\mu$ A max: 30/10 $\mu$ A to 30/10/3 $\mu$ A	M. Higuchi	K. Yoshizaki
4.0	Nov. 29, 1995	Ordering Information (HM62256BLFP-4 Series) Addition of note (Under development) AC Characteristics Test Conditions HM62256-5/7/8:1TTL Gate + $C_L$ (100pF) to HM62256-5:1TTL Gate + $C_L$ (50pF) and HM62256-7/8:1TTL Gate + $C_L$ (100pF)	M. Higuchi	K. Yoshizaki
5.0	Jul. 9, 1997	Change of format Deletion of HM62256B-4 Series	M. Higuchi	K. Imato
6.0	Nov. 13,1997	Operation Table Correct Error DC Operating Conditions Correct Error DC Characteristics Correct Error		